

Test Research, Inc. (TRI), a leading test and inspection systems provider for the electronics manufacturing industry, returns to Nepcon South China 2014 with a powerful and cost-effective product lineup that encompasses a full range of solutions for inspecting and testing PCB assemblies. Test Research, Inc. invites you to visit **Booth No. C02**, from **August 26-28, 2014** at **Shenzhen Convention & Exhibition Center (Hall 1)** for an on-site demonstration of the following systems.

德律科技为测试与检测设备的领导品牌, 将以强大并具绝佳成本效益的产品阵容, 于「第二十届华南国际电子生产设备暨微电子工业展」展示全方位的组装电路板测试与检测方案, 德律科技在此邀请您于 8/26 - 8/28 前来深圳会展中心(1 号馆)参观摊位 C02, 我们将在现场展示以下机台:



TR7007 SII Dual Lane 3D SPI

- Ultimate Dual Lane 3D SPI Solution
- Industry Leading Inspection Speed
- Super High Resolution and Accuracy
- Ultra Low Bridge Detection
- Smart 5-step Easy Programming
- Closed Loop Integration



TR7500 SIII 3D AOI

- Total Coverage 2D + Multi Angle 3D AOI
- True 3D Profile Measurement
- 5 High Resolution Color Cameras
- Fully Automated Easy Programming
- High Performance Design for Automotive and HDI



TR7700M SIII AOI

- High Speed Multi-Phase Inspection
 - 10 μ m 60 cm²/sec
 - 15 μ m 120 cm²/sec
- Fully Automated Intelligent Programming
- Auto-tuning Intelligent Automated Conveyor System



TR7702 SII DT AOI

- High Performance Desktop Color AOI
- M-size board 6.7s at 18 μ m
- Large 4MP Color Camera
- Fine-Pitch / 01005 Component Ready
- Inspects Boards up to 330 x 250 mm
- Large Board Clearance up to 100 mm



YMS LITE

- Defect Image Analysis & Reporting
- SPI, Pre/Post-reflow AOI & AXI Integration
- Centralized Alarm Management

TR518 SII INLINE MDA

- Compact MDA for Small Boards up to 1024 Points
- Cost Effective Inline Platform
- High Speed Analog Testing
- Modular MDA Configuration
- Intelligent Board Handling for Damage Prevention
- Bypass Conveyor for Multiple Inline Testers



TR5001T SII TINY ICT

- World's Most Powerful Tiny ICT
- Best Cost Cutting Solution
- Multi-ICT Parallel Testing
- Boundary Scan Test
- Serial Device Programming
- Advanced Analog and Digital Testing with Programmable DUT Power Supplies



TR7600 SII 3D AXI

- High-speed Inline 3D X-ray Inspection
- High Resolution Mode for 01005 Components
- BGA, PoP, Press-fit, PTH, QFN, Inspection
- Automated CAD-based or Manual Programming with Auto Tuning
- Multiple Resolutions in One Program
- Board Size up to 900 x 460 mm
- Block Scan 3D Slice Imaging

